



RE212-LF

- Epoxy fibre-glass FR4 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL-leadfree)
- Soldering stop mask
- Hole spacing 2.54 x 2.54 mm
- 38 x 61 soldering pads 2.10 mm Ø
- Hole diameter 1.00 mm
- All soldering pads are connected by horizontal and vertical conductor paths
- Manual interruption of the thin conductor paths enables the simple creation of custom layouts
- Size 100 x 160 mm